



Material Content Data Sheet



Sales Product Name	BA 895 H6327			Issued		29. August 2013		
MA#	MA000770644							
Package	PG-SCD80-2-1			Weight*		1.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		33	
	noble metal	gold	7440-57-5	0.006	0.32		3230	
	inorganic material	silicon	7440-21-3	0.052	2.76	3.08	27585	30848
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		395	
	non noble metal	chromium	7440-47-3	0.002	0.12		1185	
	non noble metal	copper	7440-50-8	0.744	39.33	39.50	393310	394969
wire	non noble metal	copper	7440-50-8	0.002	0.12	0.12	1165	1165
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5085	
	plastics	epoxy resin	-	0.164	8.64		86448	
	inorganic material	silicondioxide	60676-86-0	0.789	41.70	50.85	416982	508515
leadfinish	non noble metal	tin	7440-31-5	0.036	1.90	1.90	19027	19027
plating	noble metal	silver	7440-22-4	0.086	4.55	4.55	45476	45476
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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